NEW PRODUCT

# DMT3008LFDF

**30V N-CHANNEL ENHANCEMENT MODE MOSFET**

## Product Summary

| $V_{(BR)DSS}$ | $R_{DS(ON)\ max}$ | $I_{D\ max}$ $T_A$ = +25°C |
|---|---|---|
| 30V | 10mΩ @ $V_{GS}$ = 10V | 12.0A |
| | 16mΩ @ $V_{GS}$ = 4.5V | 10.4A |

## Description

This new generation MOSFET is designed to minimize the on-state resistance ($R_{DS(ON)}$) and yet maintain superior switching performance, making it ideal for high efficiency power management applications.

## Applications

- General Purpose Interfacing Switch
- Power Management Functions

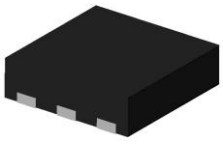
## Features

- 0.6mm Profile – Ideal for Low Profile Applications
- PCB Footprint of 4mm$^2$
- Low Gate Threshold Voltage
- Low On-Resistance
- **Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)**
- **Halogen and Antimony Free. "Green" Device (Note 3)**

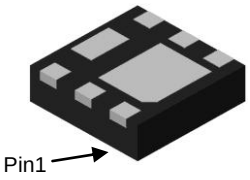
## Mechanical Data

- Case: U-DFN2020-6
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish – NiPdAu over Copper Leadframe. Solderable per MIL-STD-202, Method 208 e4
- Weight: 0.0065 grams (Approximate)

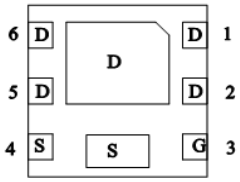
**U-DFN2020-6**



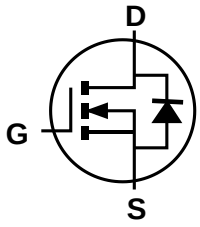
Top View




Bottom View




Pin Out
Bottom View




Equivalent Circuit

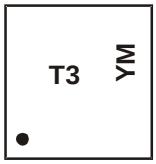
## Ordering Information (Note 4)

| Part Number | Marking | Reel size (inches) | Quantity per reel |
|---|---|---|---|
| DMT3008LFDF-7 | T3 | 7 | 3,000 |
| DMT3008LFDF-13 | T3 | 13 | 10,000 |

Notes:
1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
2. See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
4. For packaging details, go to our website at http://www.diodes.com/products/packages.html.

## Marking Information

**U-DFN2020-6**




T3 = Product Type Marking Code
YM = Date Code Marking
Y = Year (ex: B = 2014)
M = Month (ex: 9 = September)

Date Code Key

| Year | 2014 | 2015 | 2016 | 2017 | 2018 | 2019 | 2020 | 2021 |
|---|---|---|---|---|---|---|---|---|
| Code | B | C | D | E | F | G | H | I |

| Month | Jan | Feb | Mar | Apr | May | Jun | Jul | Aug | Sep | Oct | Nov | Dec |
|---|---|---|---|---|---|---|---|---|---|---|---|---|
| Code | 1 | 2 | 3 | 4 | 5 | 6 | 7 | 8 | 9 | O | N | D |

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## Maximum Ratings (@$T_A$ = +25°C, unless otherwise specified.)

| Characteristic | | | Symbol | Value | Units |
|---|---|---|---|---|---|
| Drain-Source Voltage | | | $V_{DSS}$ | 30 | V |
| Gate-Source Voltage | | | $V_{GSS}$ | ±20 | V |
| Continuous Drain Current (Note 6) $V_{GS}$ =10.0V | Steady State | $T_A$ = +25°C<br>$T_A$ = +70°C | $I_D$ | 12.0<br>9.5 | A |
| | t<10s | $T_A$ = +25°C<br>$T_A$ = +70°C | $I_D$ | 13.6<br>11.0 | A |
| Continuous Drain Current (Note 6) $V_{GS}$ = 4.5V | Steady State | $T_A$ = +25°C<br>$T_A$ = +70°C | $I_D$ | 10.4<br>8.4 | A |
| | t<10s | $T_A$ = +25°C<br>$T_A$ = +70°C | $I_D$ | 11.9<br>9.6 | A |
| Pulsed Drain Current (10µs pulse, duty cycle = 1%) | | | $I_{DM}$ | 70 | A |
| Maximum Body Diode Continuous Current | | | $I_S$ | 2 | A |
| Avalanche Current (Note 7) L = 0.1mH | | | $I_{AS}$ | 8 | A |
| Avalanche Energy (Note 7) L = 0.1mH | | | $E_{AS}$ | 3.2 | mJ |

## Thermal Characteristics

| Characteristic | | Symbol | Value | Units |
|---|---|---|---|---|
| Total Power Dissipation (Note 5) | $T_A$ = +25°C | $P_D$ | 0.8 | W |
| | $T_A$ = +70°C | | 0.5 | |
| Thermal Resistance, Junction to Ambient (Note 5) | Steady State | $R_{\theta JA}$ | 156 | °C/W |
| | t<10s | | 116 | |
| Total Power Dissipation (Note 6) | $T_A$ = +25°C | $P_D$ | 2.1 | W |
| | $T_A$ = +70°C | | 1.3 | |
| Thermal Resistance, Junction to Ambient (Note 6) | Steady State | $R_{\theta JA}$ | 60.8 | °C/W |
| | t<10s | | 45.0 | |
| Thermal Resistance, Junction to Case (Note 6) | | $R_{\theta JC}$ | 13 | |
| Operating and Storage Temperature Range | | $T_J$, $T_{STG}$ | -55 to +150 | °C |

## Electrical Characteristics (@$T_A$ = +25°C, unless otherwise specified.)

| Characteristic | Symbol | Min | Typ | Max | Unit | Test Condition |
|---|---|---|---|---|---|---|
| **OFF CHARACTERISTICS (Note 8)** | | | | | | |
| Drain-Source Breakdown Voltage | $BV_{DSS}$ | 30.0 | — | — | V | $V_{GS}$ = 0V, $I_D$ = 250µA |
| Zero Gate Voltage Drain Current $T_J$ = +25°C | $I_{DSS}$ | — | — | 1.0 | µA | $V_{DS}$ = 24V, $V_{GS}$ = 0V |
| Gate-Source Leakage | $I_{GSS}$ | — | — | ±100 | nA | $V_{GS}$ = ±20V, $V_{DS}$ = 0V |
| **ON CHARACTERISTICS (Note 8)** | | | | | | |
| Gate Threshold Voltage | $V_{GS(TH)}$ | 1.0 | — | 3.0 | V | $V_{DS}$ = $V_{GS}$, $I_D$ = 250µA |
| Static Drain-Source On-Resistance | $R_{DS(ON)}$ | — | — | 10.0 | mΩ | $V_{GS}$ = 10V, $I_D$ = 9.0A |
| | | | — | 16.0 | | $V_{GS}$ = 4.5V, $I_D$ = 8.5A |
| Diode Forward Voltage | $V_{SD}$ | — | — | 1.2 | V | $V_{GS}$ = 0V, $I_S$ = 2A |
| **DYNAMIC CHARACTERISTICS (Note 9)** | | | | | | |
| Input Capacitance | $C_{iss}$ | — | 886 | — | pF | $V_{DS}$ = 15V, $V_{GS}$ = 0V, f = 1.0MHz |
| Output Capacitance | $C_{oss}$ | — | 531 | — | pF | |
| Reverse Transfer Capacitance | $C_{rss}$ | — | 53 | — | pF | |
| Gate Resistance | $R_g$ | — | 1.6 | — | Ω | $V_{DS}$ = 0V, $V_{GS}$ = 0V, f = 1.0MHz |
| Total Gate Charge ($V_{GS}$ = 10V) | $Q_g$ | — | 14 | — | nC | $V_{DD}$ = 10V, $I_D$ = 30A |
| Total Gate Charge ($V_{GS}$ = 4.5V) | $Q_g$ | — | 5.8 | — | nC | |
| Gate-Source Charge | $Q_{gs}$ | — | 2.6 | — | nC | |
| Gate-Drain Charge | $Q_{gd}$ | — | 2.5 | — | nC | |
| Turn-On Delay Time | $t_{D(ON)}$ | — | 3.8 | — | ns | $V_{DD}$ = 10V, $V_{GS}$ = 10V, $R_L$ = 0.67Ω, $R_G$ = 4.7Ω, $I_D$ = 15A |
| Turn-On Rise Time | $t_R$ | — | 1.7 | — | ns | |
| Turn-Off Delay Time | $t_{D(OFF)}$ | — | 12.5 | — | ns | |
| Turn-Off Fall Time | $t_F$ | — | 3.6 | — | ns | |
| Reverse Recovery Time | $t_{RR}$ | — | 18.4 | — | ns | $I_F$ = 15A, dI/dt = 100A/µs |
| Reverse Recovery Charge | $Q_{rr}$ | — | 7.6 | — | nC | |

Notes:
5. Device mounted on FR-4 substrate PC board, 2oz copper, with minimum recommended pad layout.
6. Device mounted on FR-4 substrate PC board, 2oz copper, with 1inch square copper plate.
7. $I_{AS}$ and $E_{AS}$ rating are based on low frequency and duty cycles to keep $T_J$ = +25°C.
8. Short duration pulse test used to minimize self-heating effect.
9. Guaranteed by design. Not subject to product testing.

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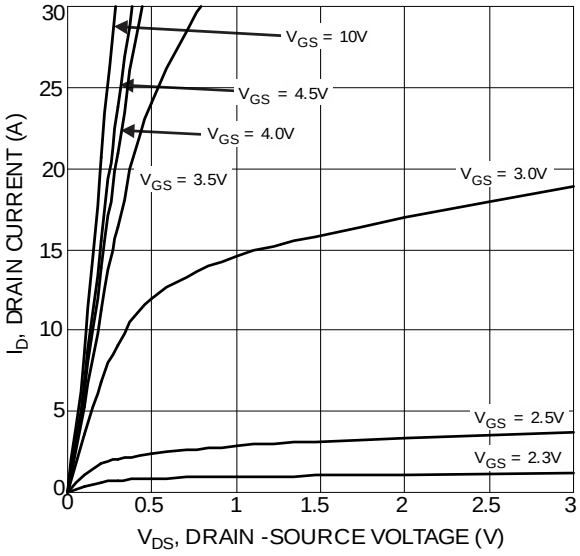


Figure 1 Typical Output Characteristics

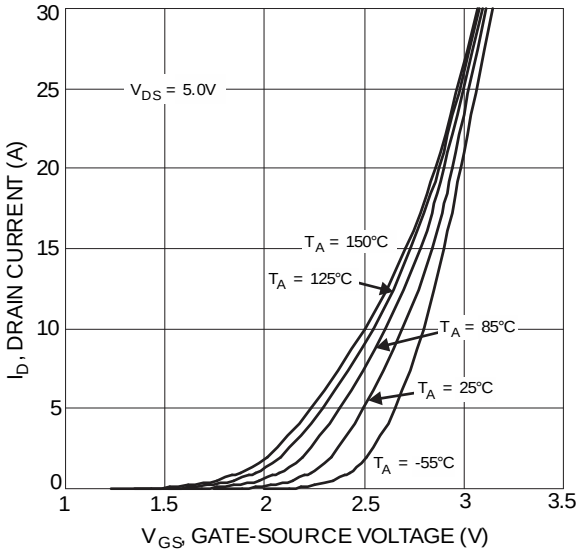


Figure 2 Typical Transfer Characteristics

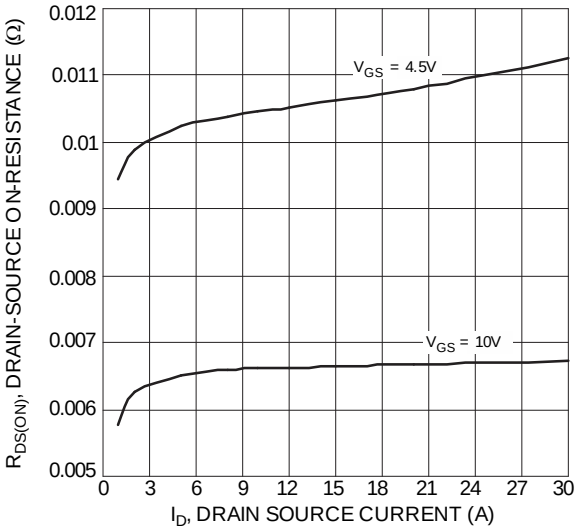


Figure 3 Typical On-Resistance vs. Drain Current and Gate Voltage

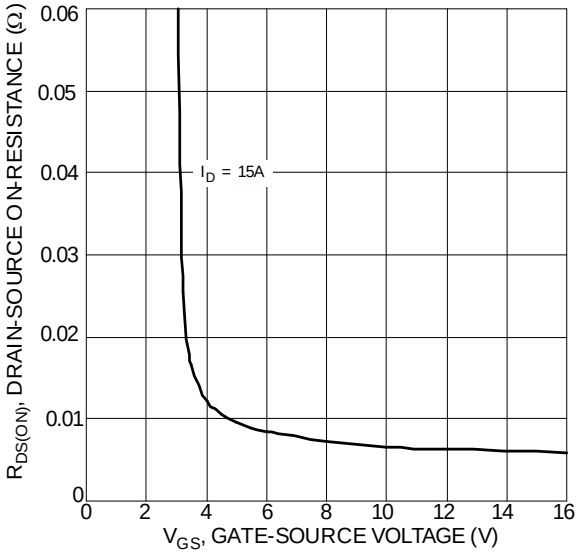


Figure 4 Typical Transfer Characteristic

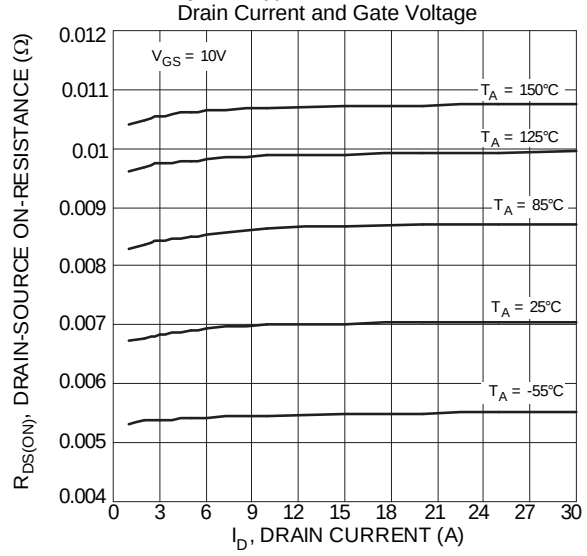


Figure 5 Typical On-Resistance vs. Drain Current and Temperature

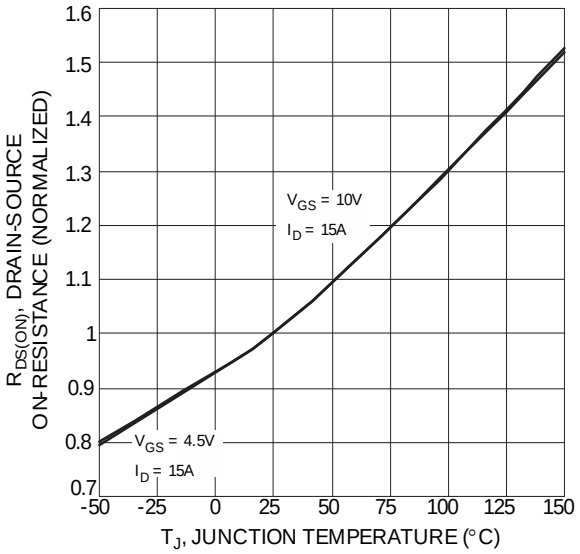


Figure 6 On-Resistance Variation with Temperature

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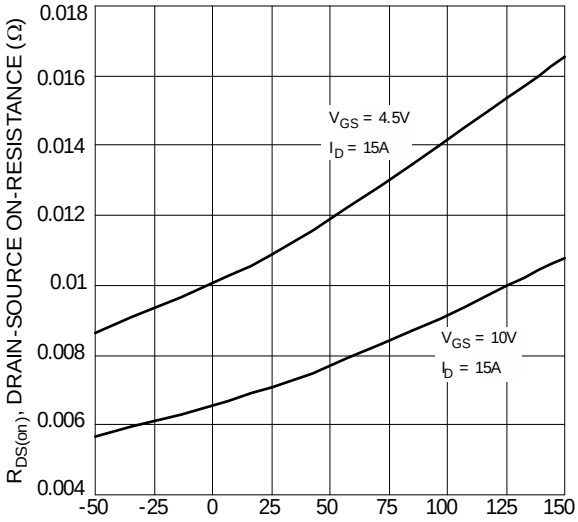


Figure 7 On-Resistance Variation with Temperature

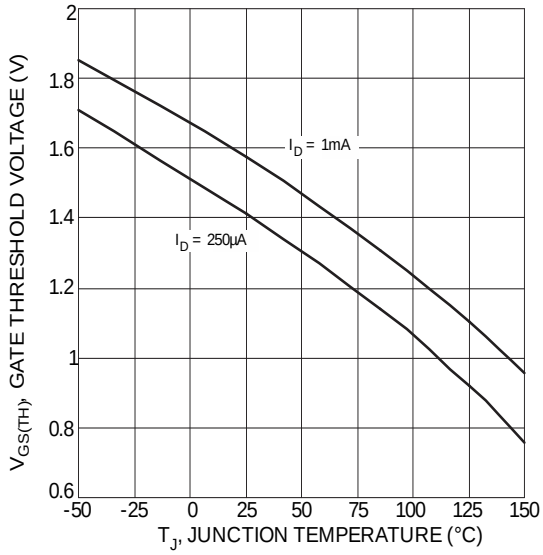


Figure 8 Gate Threshold Variation vs. Junction Temperature

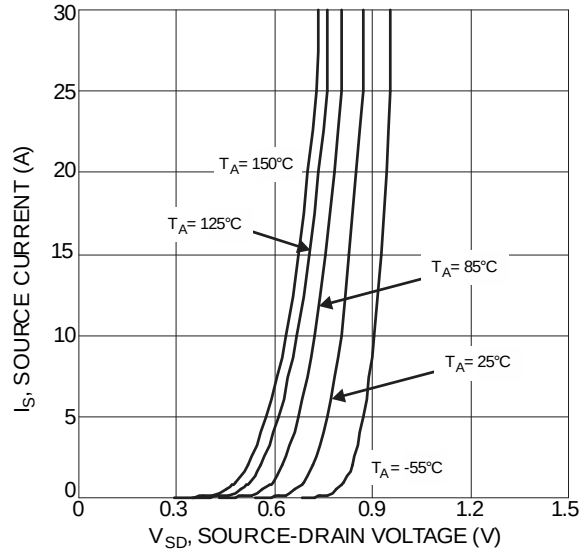


Figure 9 Diode Forward Voltage vs. Current

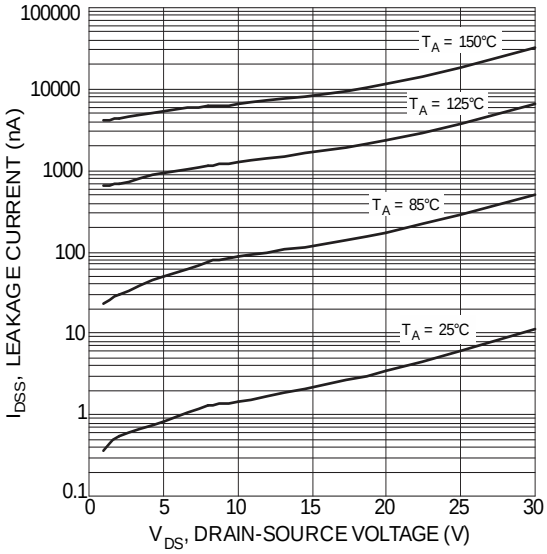


Figure 10 Typical Drain-Source Leakage Current vs. Voltage

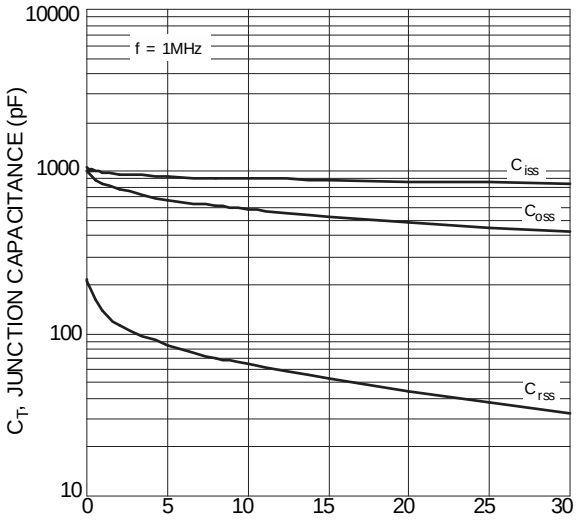


Figure 11 Typical Junction Capacitance

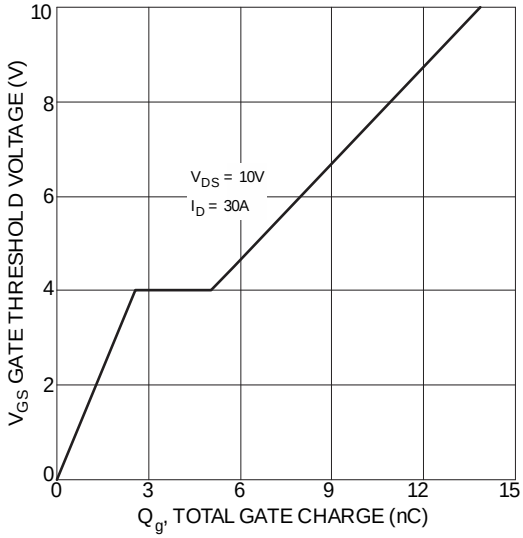


Figure 12 Gate Charge

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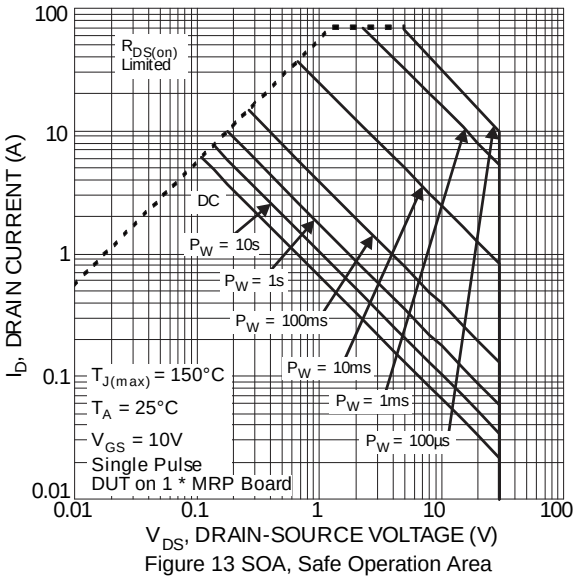


Figure 13 SOA, Safe Operation Area

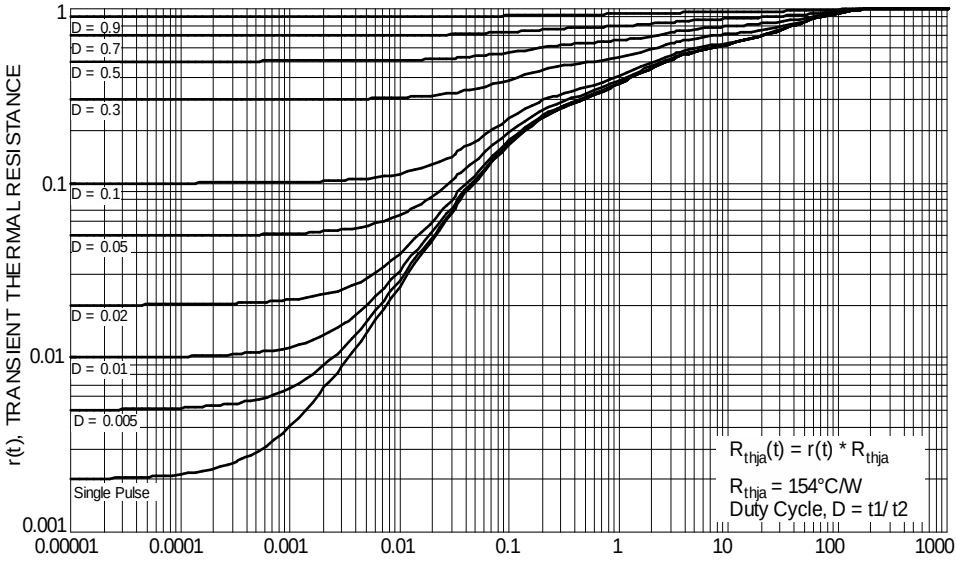


Figure 14 Transient Thermal Resistance

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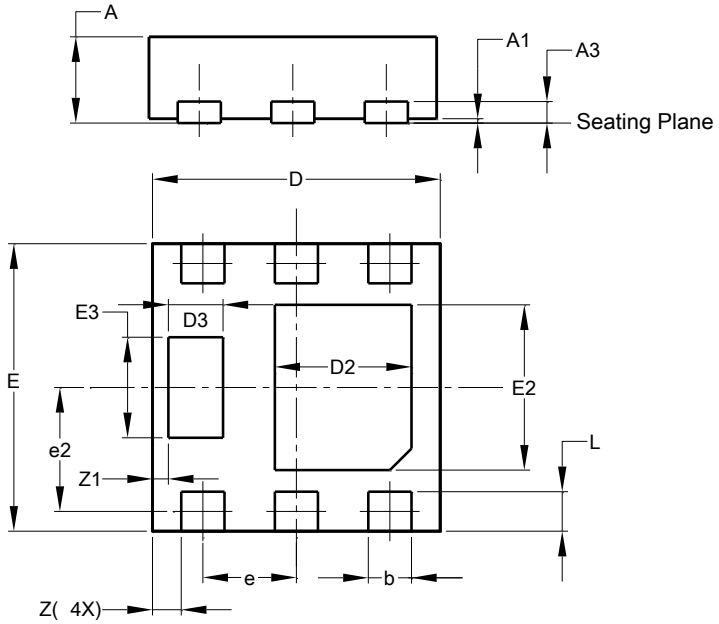
## Package Outline Dimensions

Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for the latest version.

**(1) Package Type: U-DFN2020-6 (Type F)**

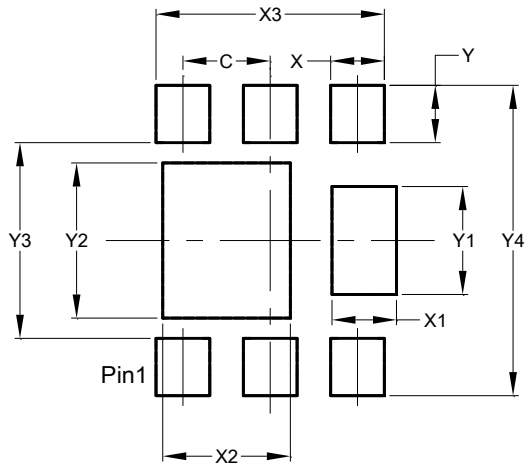



| U-DFN2020-6 (Type F) | | | |
|---|---|---|---|
| **Dim** | **Min** | **Max** | **Typ** |
| **A** | 0.57 | 0.63 | 0.60 |
| **A1** | 0 | 0.05 | 0.03 |
| **A3** | - | - | 0.15 |
| **b** | 0.25 | 0.35 | 0.30 |
| **D** | 1.95 | 2.05 | 2.00 |
| **D2** | 0.85 | 1.05 | 0.95 |
| **D3** | 0.33 | 0.43 | 0.38 |
| **e** | 0.65 BSC | | |
| **e2** | 0.863 BSC | | |
| **E** | 1.95 | 2.05 | 2.00 |
| **E2** | 1.05 | 1.25 | 1.15 |
| **E3** | 0.65 | 0.75 | 0.70 |
| **L** | 0.225 | 0.325 | 0.275 |
| **Z** | 0.20 BSC | | |
| **Z1** | 0.110 BSC | | |
| **All Dimensions in mm** | | | |

## Suggested Pad Layout

Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for the latest version.

**(1) Package Type: U-DFN2020-6 (Type F)**




| Dimensions | Value (in mm) |
|---|---|
| **C** | 0.650 |
| **X** | 0.400 |
| **X1** | 0.480 |
| **X2** | 0.950 |
| **X3** | 1.700 |
| **Y** | 0.425 |
| **Y1** | 0.800 |
| **Y2** | 1.150 |
| **Y3** | 1.450 |
| **Y4** | 2.300 |

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